

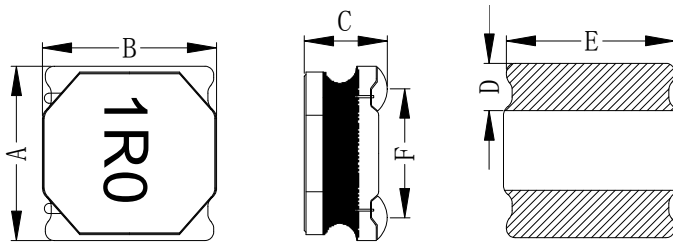
SMD Power Inductor **HPC6028NV-Series**

1. Features

1. This specification applies Low Profile Power Inductors.
2. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
3. High reliability -Reliability test meet AEC-Q200.
4. Operating temperature: -55~+125°C (Including self-temperature rise)



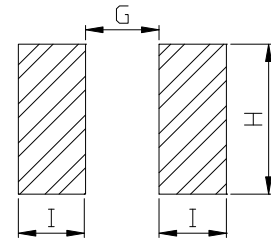
2. Dimensions



Series	*A(mm)	*B(mm)	*C(mm)	D(mm)	E(mm)	F(mm)
HPC6028NV	6.0±0.2	6.0±0.2	2.6±0.2	1.6±0.3	5.8±0.3	4.3ref

*Dimensions are not including the termination. For maximum overall dimensions with termination, add 0.1mm.

Recommended Land pattern



G(mm)	H(mm)	I(mm)
2.5	5.8	1.8

Note: 1. The above PCB layout reference only.
 2. Recommend solder paste thickness at 0.15mm and above.

3. Part Numbering



- A: Series
 - B: Dimension
 - C: Type
 - D: Inductance
 - E: Inductance Tolerance
- A/B*C
 V=Vehicle
 1R0=1.0uH
 Y=±30%.
 marking direction cannot decide polarity. Color: Black, unidirectional.
 magnetic shielding

4. Specification

Part Number	Inductance L0 (uH) @ 0 A	Tolerance	Rated current		DCR (mΩ) @25°C ±20%.
			Temperature current I rms (A)	Saturation current I sat (A)	
HPC6028NV-1R0Y	1.00	±30%	5.20	5.75	10.0
HPC6028NV-1R5Y	1.50	±30%	4.95	5.30	14.0
HPC6028NV-2R2M	2.20	±20%	4.50	5.00	18.0
HPC6028NV-3R3M	3.30	±20%	3.60	4.30	24.0
HPC6028NV-4R7M	4.70	±20%	3.10	3.20	30.0
HPC6028NV-6R8M	6.80	±20%	2.50	2.85	47.0
HPC6028NV-100M	10.0	±20%	2.00	2.10	65.0
HPC6028NV-150M	15.0	±20%	1.80	2.00	98.0
HPC6028NV-220M	22.0	±20%	1.50	1.60	138
HPC6028NV-330M	33.0	±20%	1.30	1.40	200
HPC6028NV-470M	47.0	±20%	1.06	1.15	280
HPC6028NV-680M	68.0	±20%	0.81	1.00	420
HPC6028NV-101M	100	±20%	0.72	0.80	605

Note:

1. All test data referenced to 25°C ambient , Ls:100KHz/1V.
2. Testing Instrument : HP4284A,CH11025,CH3302,CH1320 ,CH1320S LCR METER / Rdc:CH502BC MICRO OHMMETER.
3. Heat Rated Current (Irms) will cause the coil temperature rise approximately Δt of 40°C
4. Saturation Current (Isat) will cause L0 to drop approximately 30%
5. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
6. Special inquiries besides the above common used types can be met on your requirement.

5. Typical Performance Curves

